(%) OFFFDENOT

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PREPARED BY:	DATE:			SPEC. N	O. DG-958041	
Mr. Yabe	Aug. 10. 95	SHA		ISSUE	Aug. 10, 1995	
APPROVED BY:	DATE:	ELECTRONIC COM		PAGE	8 Pages	
M. abe	aug ,10, ⁹⁵	SHARP CORPORA?	_	REPRESENTATIVE DIVISION OPTO-ELECTRONIC DEVICES DIV.		
	DEVICE S	SPECIFICATION FOR GaP Yellow-green Chip LED Device LT1E 67A	m			
z. Please ob and the r for any d and note	ey the absolute maximum office mentioned below lamage caused by imply setc. in these special device is designed for the communication among those applications.	equipment (Terminal) Computer eations, if there is applic	on these specification evice, SHARP takes no viated from the absolutice mentioned below explications; Home appliance Yeascring equipment	on sheets, responsibility utemaximum ratin for actual use o	narp"). ause g f this device.	
safer	ty design of overall and safety in the function con Traffic signal Other safety equip	such as fail-safe design a system and equipment, sunction and precision when a safety equipment Gas leakage sensor breakament, etc.	hould be taken to ensual this device is used (aircraft, train, automorer Fire box and but the control of the co	re the reliability for equipment. so obile etc.) arglar alarm box	Such #3:	
	Space equipment "Nuclear power cont	"Telecommunication equipment ● Mediml e	nent (Trunk)			
	-	a Sharp representative if any applications listed ab	· · —	ns when intendi the listed above.	ng	
		arp representative, in advan	_			
CUSTO	MER'S APPROVAL		DATE PRESENTED BY	Aug.10.1 M.Abe	P	
DATE			M.Abe Departm	entGeneral M	lanager of	
BY			Enginee Opto-E1 EL ECOM	ring Dept., III ectronic Devi	-	

LT1E67A

PAGE 1

SHARP

LT1E67A

This data sheet is to introduce the light emitting diode device Model No. LT1E67A, delivered to

I.Structure and characteristics

Structure: GaP yellow-green chip LED device

Outline dimensions and pin connections: See page 2

· Taping specification:

See page 343 6

Packing specification: Soldering method:

See page 7
See page 8

2. A bsolute maximum ratings

(Ta=2.5%)

Z. A psolute maximum	n raungs		1a-200	
Parameter		Symbol	Value	Unit
Power dissipation		P	84_	mW
Continuous forward	l current	I F	<u>3</u> 0	шA
Peak forward curre	nt(Note 1)	IFM	5 0	m A
Derating factor	DC	_	0.40	mA/°C
	Pulse	_	0.67	mA/°C
Reverse voltage		V _R	5	V
Operating temperat	ure	T opr	-30~+ 85	౮
Storage temperature)	Tstg	$-40 \sim +100$	రి

(Note 1) Duty ratio = 1/10, Pulse width = 0.1 as

3. Electro optical characteristics

(Ta = 2 5 c)

Parameter	Symbol	Conditions	Min.	Тур.	Nax.	Unit
Forward voltage	VF	$I_F = 20 \text{ mA}$	_	2.1	2.8	V
Luminous intensity	Ιv			All articles to the control of the c		
(Note 2)			4.5	11	<u>_</u>	mcd
Peak emission	λp					
wavelength				565		'm
Spectrum radiation	Δλ					
bandwidth				30 _	-	nm
Reverse current	IR	V _R = 4 V	-		10	μΑ
Terminal capacitance	Ct	V = 0V, $f = 1MIZ$	-	35	-	_ pF

(Note 2) Torelance: ±15%

4 Luminous intensity rank

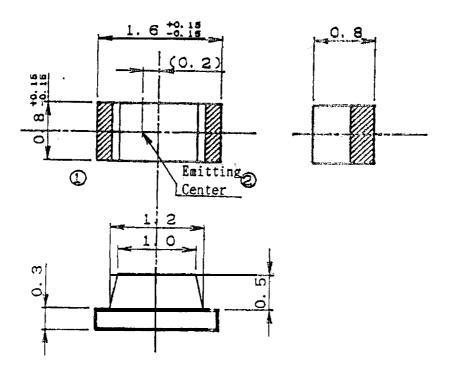
r	$\underline{\underline{ (\underline{\Upsilon} a = 25^{\circ}\underline{C})}$	
Rank:Luminous intensity	Unit Condition	
A 4.5 8.7	programme	
B $6.5 \sim 12.5$	IF = 20mA	J
C 9.4 ~ 18.1	mcd tolerance; ±15%	
D 1 3.4 ~ 26.1		- 1
E 19.4 ~ 37.7	<u> </u>	

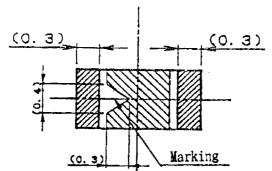
(Note3) Measured by SHARP EC&G MODEL550 (Radiometer/Photometersys tern)

REFERENCE

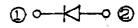
SHARP

PAGE 2





- 1. Plated area Resist area
- 2. Pin Conection
 - a Cathode
 - 2 Anode

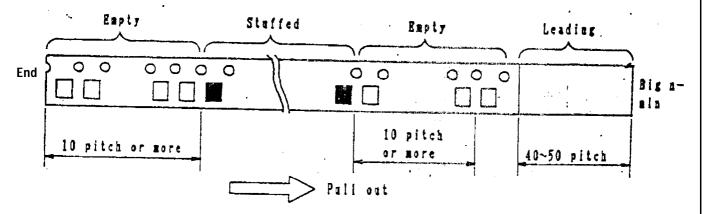


3. Unspecified tel. to be ± 0.1

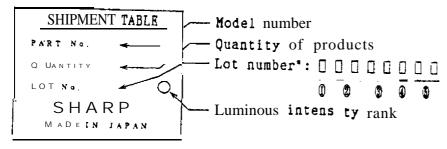
			<u> </u>	[
LT1E67A	20/1	mm	SAME DI	E SUISE SEATS 指示CHNG	
FTHICKNESS 員数 PHECES	材質 MATERIAL	tt Finish	.5 2-	Outline dimensions and	
	Auめっき		名称 NAMB	terminal connections	
DATE 1995. 4.25		注電子部品車送本部	コード		
計 製図 校図 校図 承認	オプトテバイス OPTO-BLECTRON	(事)第3技術部	CODE		
1311/1511/134 1 1 25 2	ELECO	RPORATION	図 番 DRAWING	No. 50604026B	

· Taping Specification

- I. This data sheet is to introduce the taping specification of LED device, model No. LT1E67A
- 2. Taping specification
- 2. 1 Taping specification



2.2 Shipment table



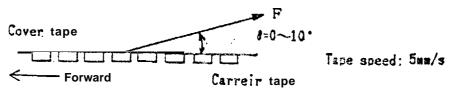
- *:Lot indication
 - Production plant code(to be indicated alphabetically)
 - **Production lot(single** or double figures)
 - Year of production(thelast two figures of the year)
- (co be indicated alphabetically with January corresponding to A)
- Date of production(01~31)

- 2.3 Related matters
 - 2.3.1. Packing

There should not be missing above continuous three products.

2.3.2. Tape Strength

I) Cover "tape strength against peeling: $F = 0.1 \sim 0.8 \text{N} (e=10^{\circ} \text{ or less})$.



2) Tape strength against bending

The radius of bending circle should be 30mm or more.

[f itis less than 30mm.the covertage may peel.

- 2.3.3. Taking out of products
 - 1) Products should be easily taken out.
 - 2) Products should not be attached to the cover tape at peeling.
- · 2.3.4., Jointing of tape

There should not be joint of cover tape or carrier tape.

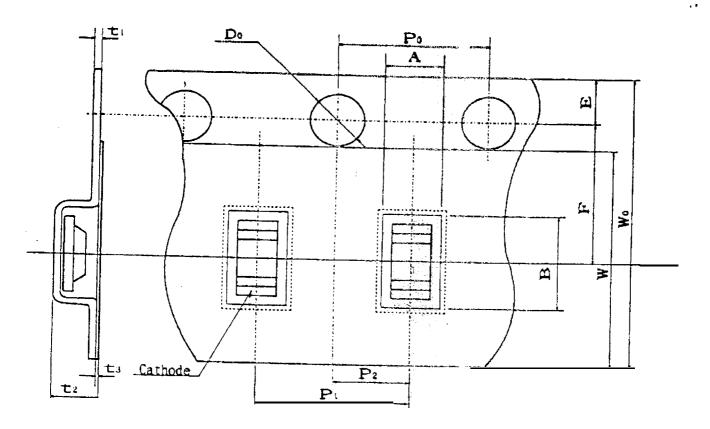
3. Quantity per reel

Average: 4,000 pcs.per reel



4-1, Taping

4-1-1. Shape and dimension of tape(TYP.).



Parameter		Symbol	Dimension	Remarks
Concave square	Vertical	A	1. Omm	Dimension excludes corner R
hole for part	Horizontal	В	1. 9mm	at inside bottom
insertion	Pitch	Pı	4. Omm	MARKALINA
Round	Diameter	DO	1. 5 mm	Constitution of the state of th
sprocket	Pitch	P*	4. On m	Accumulated error ±0.5mm/10 pitch
hole	Position	E	1.75am	Distance between tape edge and hole center
Center to cen-	Vert.dire	$\mathbf{p}_{\scriptscriptstyle 2}$	2. Oans	Center line of the concave square hole and
ter dimensio,	Hori.dire	F	3. 5 aa	round sprockethole
Cover tape	Width	W ₁	5. 5mm	· · · · · · · · · · · · · · · · · · ·
	Thickness	ŧ3	O. 1mm	<u> </u>
Carrier tape	Width	Wo	8. Omm	Allego and the contraction of th
•	Thickness	t į	0. 200	The state of the s
Thickness of the	e entire		ĺ	White depressions
unit		t ₂	1.200	With 'cover tape and carries tapeecembined

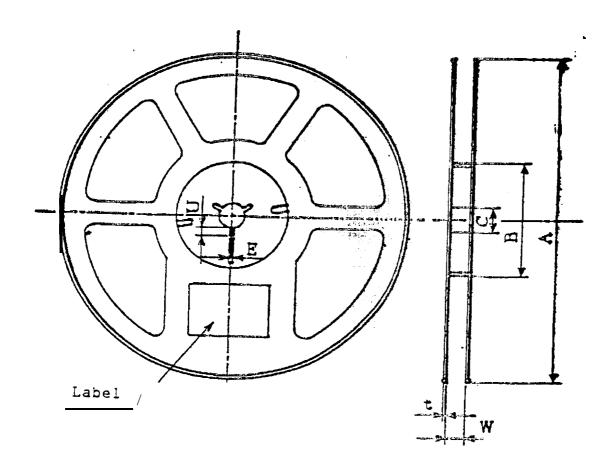
Material: Carrier tape., PET, Cover tape...Polyester

(%) REFERENCE

MODEL No. LT1E67A

SHARP

4-1-2. Shape and dimension of reel (TYP.)



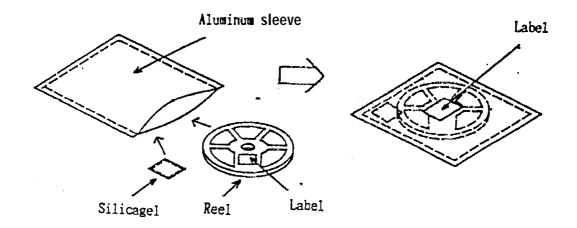
Parame	ter		Symbol	Dimension	Remarks
	Diameter		A	∮178mm	
Flange	Thickness		t	1.5mm	Refer Address of the American
	Inner space direct ion		W	10mm	Dimension of shaft core
	External d	External diameter		ø 60mm "	
Hub	Spindle hole diameter		С	ø 13mm	Bridge (statement of the statement of th
	Key slit Width		E	2.0mm	militaring distance in the control of the control o
Depth		U	4.5mm		
Notation for partname etc.			Labelin	g on one s	ide of flange.
			(Part na	ame,quantit;	y,lot No.)

▼ Material: Reel ... Polystyrene



Packing Specification

In order to avoid the absorption of humidity in transport end storage, the" devices are "packed in aluminum sleeve,



1. Storage Conditions

The storage should be done under following conditions:

Temperature 5 to 30%

Humidity less than 60%RH

- 2. Treatment after Opening
- 1) Please make a soldering within 2 days after opening under following conditions:—
 Temperature 5 to 30t

Humidity less than 60%RH

- 2) In case the devices are not used for a long time after opening, the storage in dry box is recommendable. Or it is better to repack the devices with a desiccative by the sealer and put them in the same storage conditions as 6-1. Then they should be used within 2 weeks.
- 3) Please \square akea soldering after a following baking treatment if unused term should be over the renditions of 2).

Recommendable Conditions:

① in taping

Temperature 60t Time 90 to 100 Hours

(2) in individual (on PVB or metallic tray)

Temperature 110° Time 3 to 4 Hours

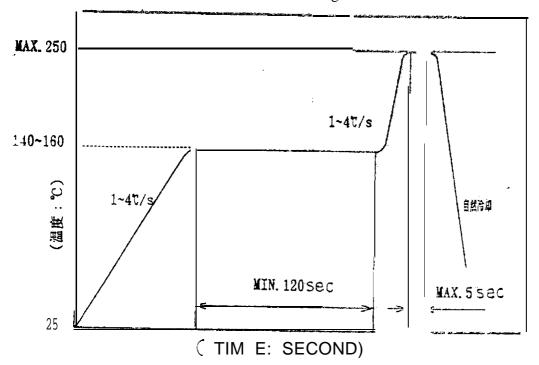
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Mounting precautions

1. Soldering

1-1 Reflowsoldering

To be done-under the following condition.



Recommendable Thermal Model

1-2 Reflow soldering precautions
Second time soldering should be done within 8 hours after the first one is finished.
(Storage condition:at30C.RH<60%)

2. Soldering iron method
At 300C within seconds

When using a soldering iron, care must be taken not to damage the package (Pay attion not to allow any undue stress or heat on package)